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(12) **United States Design Patent** (10) **Patent No.:** **US D934,158 S**
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(54) **SOLAR PANEL**

(71) Applicant: **SUNPOWER CORPORATION**, San Jose, CA (US)

(72) Inventors: **Ratson Morad**, Palo Alto, CA (US); **Gilad Almogy**, Palo Alto, CA (US); **Itai Suez**, Santa Cruz, CA (US); **Jean Hummel**, San Carlos, CA (US); **Nathan Beckett**, Oakland, CA (US)

(73) Assignee: **SUNPOWER CORPORATION**, San Jose, CA (US)

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Related U.S. Application Data

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(51) **LOC (13) Cl.** **13-02**

(52) **U.S. Cl.**
USPC **D13/102**

(58) **Field of Classification Search**
USPC D13/102, 101, 103, 110, 118, 133, 182, D13/184, 199

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Primary Examiner — Derrick E Holland
(74) *Attorney, Agent, or Firm* — Oblon, McClelland, Maier & Neustadt, L.L.P.

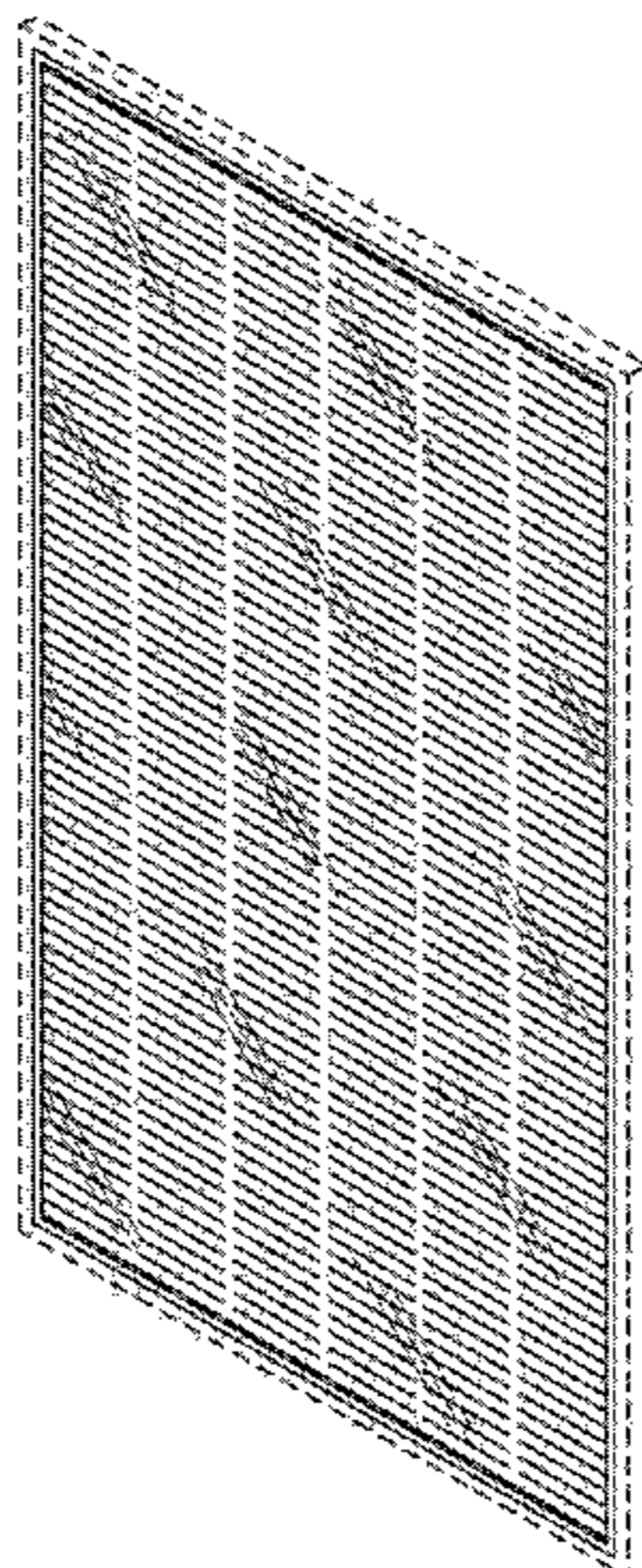
(57) **CLAIM**

The ornamental design for a solar panel, as shown and described.

DESCRIPTION

FIG. 1 is a front, top, and right side perspective view of a first embodiment of a solar panel;
FIG. 2 is a top plan view thereof, the bottom plan view being a mirror image of the top plan view shown;
FIG. 3 is a front elevational view thereof, the rear elevational view forms no part of the claimed design;
FIG. 4 is a left side elevational view thereof, the right side elevational view being a mirror image of the left side elevational view shown;
FIG. 5 is a detail view along line 5-5 in FIG. 3 of the overlapping cells thereof;
FIG. 6 is a front, top, and right side perspective view of a second embodiment of a solar panel;
FIG. 7 is a top plan view thereof, the bottom plan view being a mirror image of the top plan view shown;
FIG. 8 is a front elevational view thereof, the rear elevational view forms no part of the claimed design;
FIG. 9 is a left side elevational view thereof, the right side elevational view being a mirror image of the left side elevational view shown; and,
FIG. 10 is a detail view along line 10-10 in FIG. 8 of the overlapping cells thereof.
The broken lines in the drawings illustrate subject matter that forms no part of the claimed design.

1 Claim, 6 Drawing Sheets



Related U.S. Application Data

15/359,326, filed on Nov. 22, 2016, now Pat. No. 10,090,430, which is a continuation of application No. PCT/US2015/032472, filed on May 26, 2015, which is a continuation-in-part of application No. 14/674,983, filed on Mar. 31, 2015, now Pat. No. 9,947,820, which is a continuation-in-part of application No. 14/605,695, filed on Jan. 26, 2015, now Pat. No. 9,484,484, which is a continuation-in-part of application No. 14/594,439, filed on Jan. 12, 2015, now Pat. No. 9,397,252, which is a continuation-in-part of application No. 14/586,025, filed on Dec. 30, 2014, now abandoned, which is a continuation-in-part of application No. 14/585,917, filed on Dec. 30, 2014, now abandoned, which is a continuation-in-part of application No. 14/577,593, filed on Dec. 19, 2014, now Pat. No. 9,356,184, which is a continuation-in-part of application No. 14/572,206, filed on Dec. 16, 2014, now Pat. No. 9,401,451, which is a continuation-in-part of application No. 14/566,278, filed on Dec. 10, 2014, now abandoned, which is a continuation-in-part of application No. 14/565,820, filed on Dec. 10, 2014, now abandoned, which is a continuation-in-part of application No. 14/560,577, filed on Dec. 4, 2014, now Pat. No. 9,876,132, which is a continuation-in-part of application No. 14/552,761, filed on Nov. 25, 2014, now abandoned, which is a continuation-in-part of application No. 14/550,676, filed on Nov. 21, 2014, now abandoned, which is a continuation-in-part of application No. 29/509,588, filed on Nov. 19, 2014, now Pat. No. Des. 767,484, which is a continuation-in-part of application No. 29/509,586, filed on Nov. 19, 2014, now Pat. No. Des. 750,556, which is a continuation-in-part of application No. 14/548,081, filed on Nov. 19, 2014, now abandoned, which is a continuation-in-part of application No. 14/543,580, filed on Nov. 17, 2014, now Pat. No. 9,882,077, which is a continuation-in-part of application No. 14/539,546, filed on Nov. 12, 2014, now abandoned, which is a continuation-in-part of application No. 14/536,486, filed on Nov. 7, 2014, now abandoned, which is a continuation-in-part of application No. 29/508,323, filed on Nov. 5, 2014, now abandoned, which is a continuation-in-part of application No. 14/532,293, filed on Nov. 4, 2014, now abandoned, which is a continuation-in-part of application No. 14/530,405, filed on Oct. 31, 2014, now Pat. No. 9,780,253, which is a continuation-in-part of application No. 29/506,755, filed on Oct. 20, 2014, now abandoned, which is a continuation-in-part of application No. 29/506,415, filed on Oct. 15, 2014, now abandoned.

(58) **Field of Classification Search**

CPC Y02E 10/40; Y02E 10/44; Y02E 10/50; Y02E 10/52; Y02E 10/542; Y02E 10/544; E04H 4/08; F24J 2/38; F24J 2/0472; F24J 2/542; H01L 31/00; H01L 31/042; H01L 31/045; H01L 31/048; H01L 31/049; H01L 31/052; H01L 31/184; H01L 31/0232; H01L 31/0508; H01L 31/0512; H01L 31/0543; H01L 31/02013; H01L 31/1876; H01L 51/0061; H02S 40/34
See application file for complete search history.

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FIG. 1

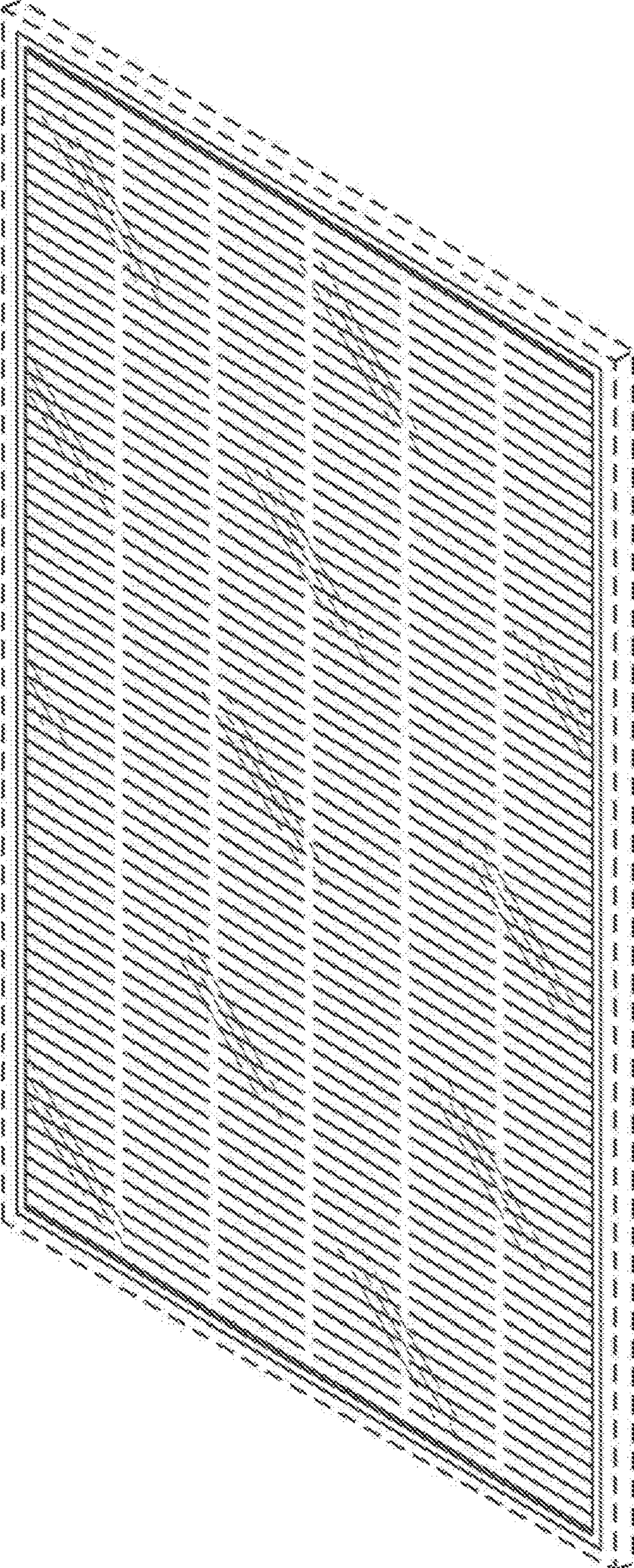


FIG. 2



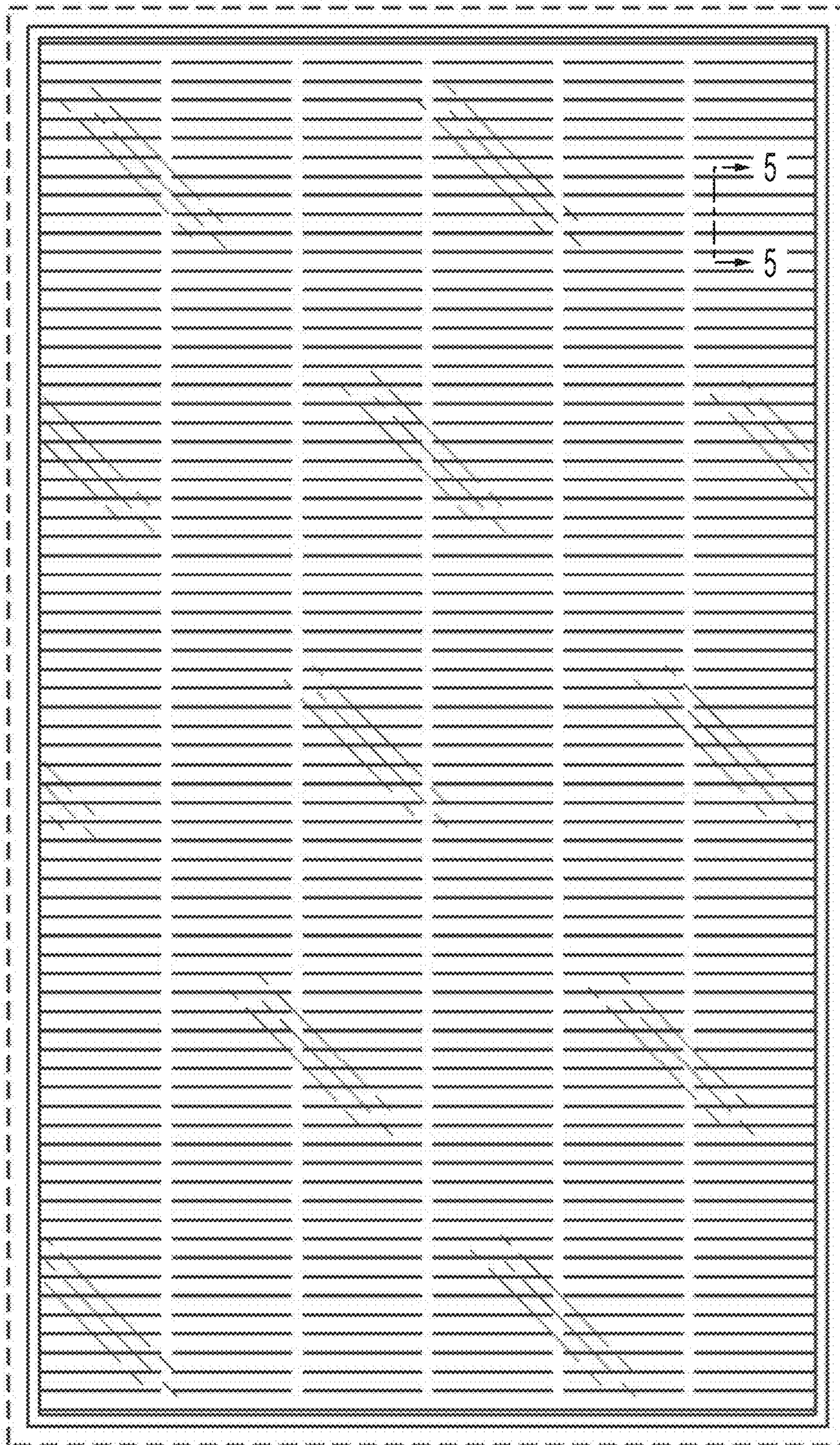


FIG. 3

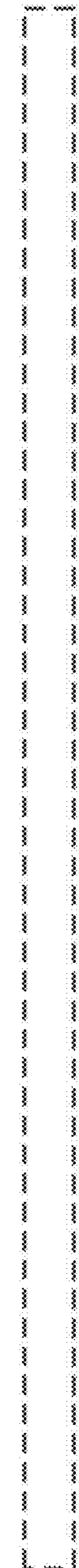


FIG. 4



FIG. 5

FIG. 6

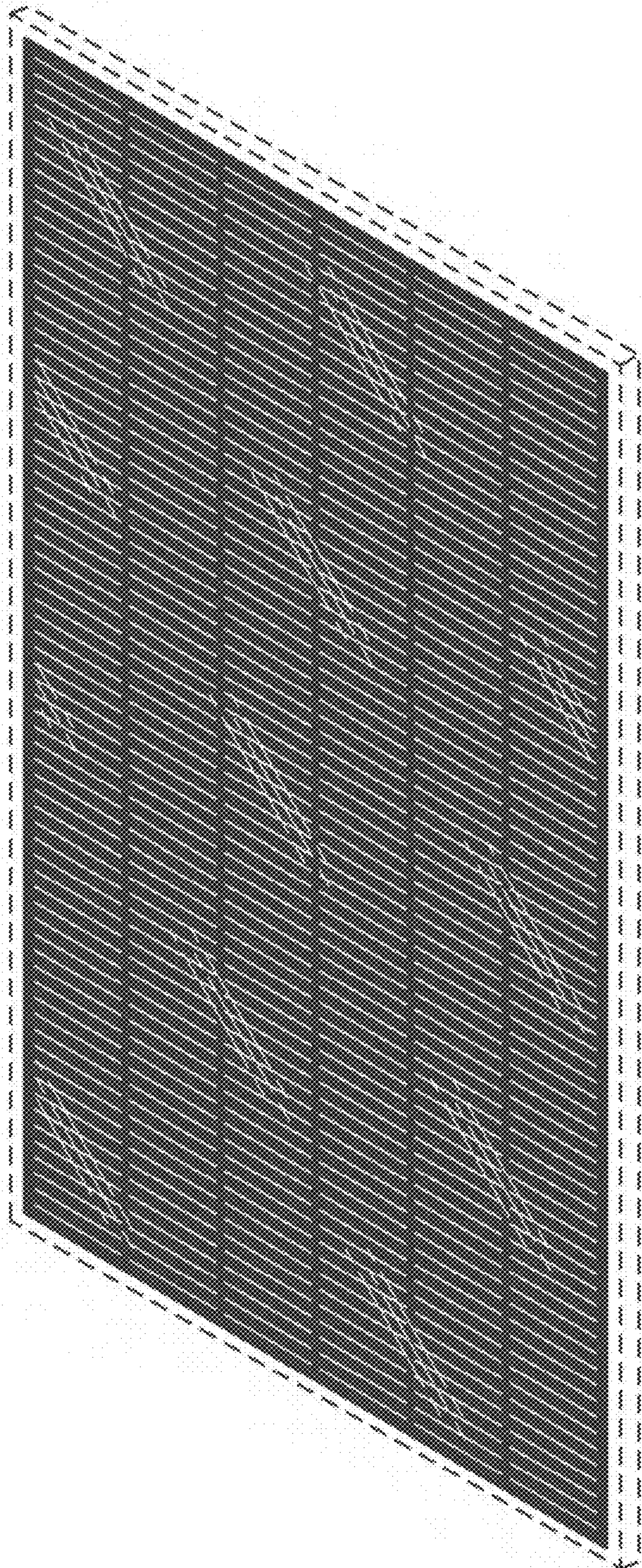
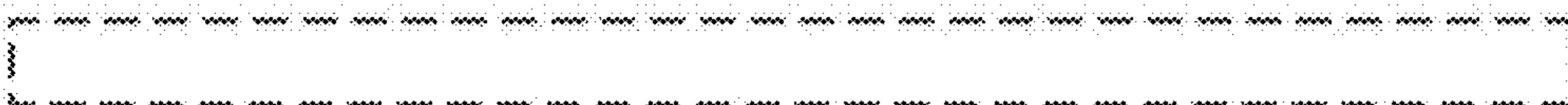


FIG. 7



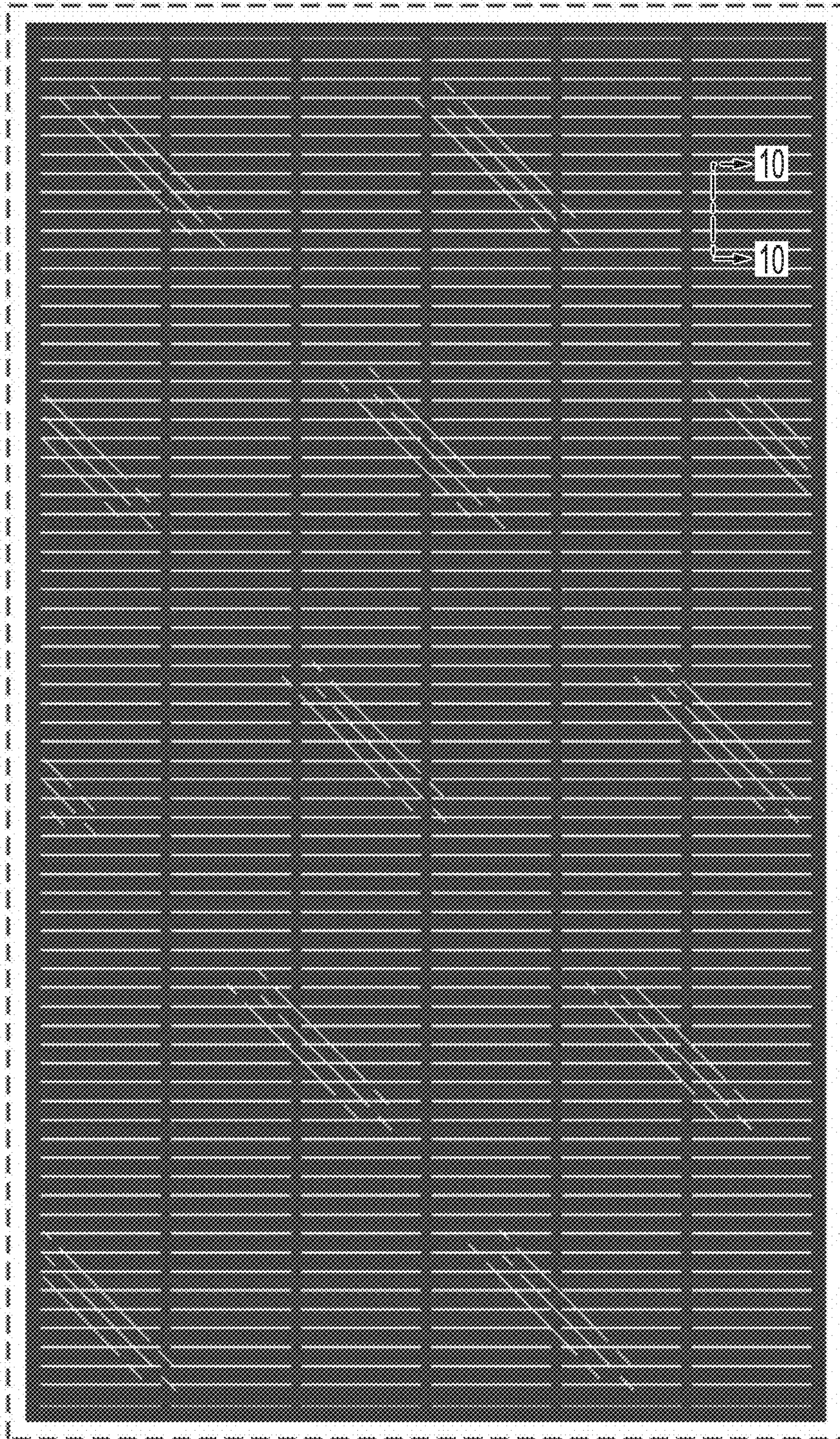


FIG. 8



FIG. 9



FIG. 10